

RJF0410JPE

40V - 40A - N Channel Thermal FET
Power Switching

R07DS1237EJ0200
Rev.2.00
Jan 29, 2015

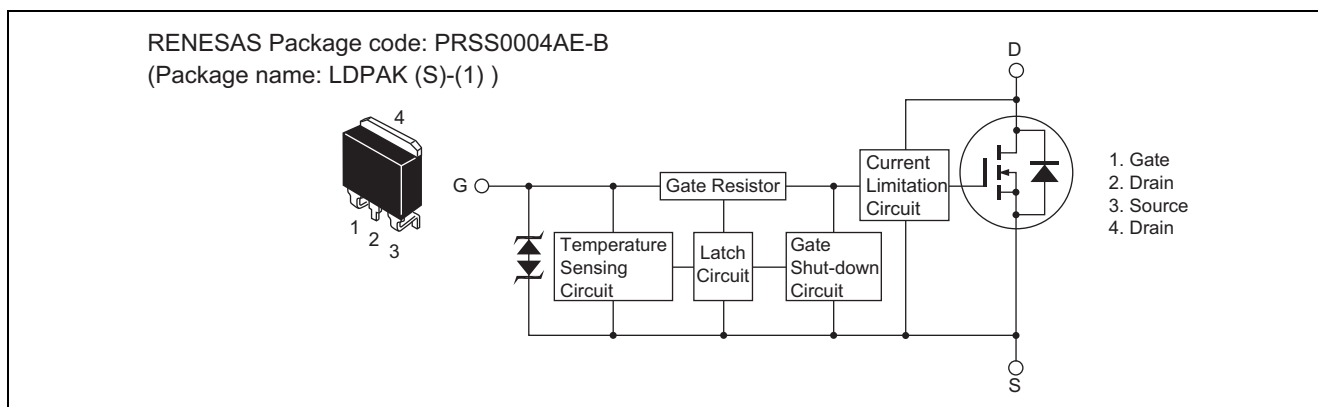
Description

This FET has the over temperature shut-down capability sensing to the junction temperature. This FET has the built-in over temperature shut-down circuit in the gate area. And this circuit operation to shut-down the gate voltage in case of high junction temperature like applying over power consumption, over current etc..

Features

- Logic level operation.
- Built-in the over temperature shut-down circuit.
- High endurance capability against to the short circuit.
- Latch type shut down operation (need 0 voltage recovery).
- Built-in the current limitation circuit.
- Power supply voltage applies 12 V.
- AEC-Q101 Compliant

Outline



Absolute Maximum Ratings

(Ta = 25°C)

| Item | Symbol | Ratings | Unit |
|----------------------------------------|-----------------------------------|-------------|------|
| Drain to source voltage | V _{DSS} | 40 | V |
| Gate to source voltage | V _{GSS} | 16 | V |
| Gate to source voltage | V _{GSS} | -2.5 | V |
| Drain current | I _D ^{Note 3} | 40 | A |
| Body-drain diode reverse drain current | I _{DR} | 40 | A |
| Avalanche current | I _{AP} ^{Note 2} | 12 | A |
| Avalanche energy | E _{AR} ^{Note 2} | 960 | mJ |
| Channel dissipation | P _{ch} ^{Note 1} | 100 | W |
| Channel temperature | T _{ch} | 150 | °C |
| Storage temperature | T _{stg} | -55 to +150 | °C |

Notes: 1. Value at T_c = 25°C
2. T_{ch} = 25°C, R_g ≥ 50 Ω
3. It provides by the current limitation lower bound value.

Typical Operation Characteristics

(Ta = 25°C)

| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
|---------------------------------------------|----------------------|-----|------|-----|------|-----------------------------------------------------------------|
| Input voltage | V _{IH} | 3.5 | — | — | V | |
| | V _{IL} | — | — | 1.2 | V | |
| Input current (Gate non shut down) | I _{IH1} | — | — | 100 | μA | V _i = 8 V, V _{DS} = 0 |
| | I _{IH2} | — | — | 50 | μA | V _i = 3.5 V, V _{DS} = 0 |
| | I _{IL} | — | — | 1 | μA | V _i = 1.2 V, V _{DS} = 0 |
| Input current (Gate shut down) | I _{IH(sD)1} | — | 0.8 | — | mA | V _i = 8 V, V _{DS} = 0 |
| | I _{IH(sD)2} | — | 0.35 | — | mA | V _i = 3.5 V, V _{DS} = 0 |
| Shut down temperature | T _{sd} | — | 175 | — | °C | Channel temperature |
| Gate operation voltage | V _{op} | 3.5 | — | 12 | V | |
| Drain current (Current limitation value) | I _{D limit} | 40 | — | — | A | V _{GS} = 5 V, V _{DS} = 10 V ^{Note 4} |

Notes: 4. Pulse test

Electrical Characteristics

(Ta = 25°C)

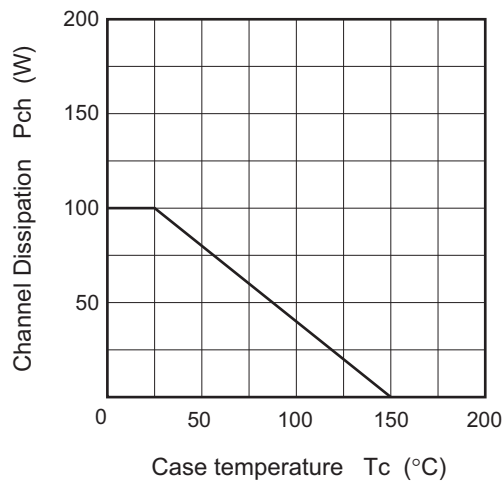
| Item | Symbol | Min | Typ | Max | Unit | Test Conditions |
|------------------------------------------------------|----------------------|------|------|------|------|-----------------------------------------------------------------------|
| Drain current | I _{D1} | — | — | 60 | A | V _{GS} = 3.5 V, V _{DS} = 10 V ^{Note 5} |
| | I _{D2} | — | — | 10 | mA | V _{GS} = 1.2 V, V _{DS} = 10 V |
| | I _{D3} | 40 | — | — | A | V _{GS} = 5 V, V _{DS} = 10 V ^{Note 5} |
| Drain to source breakdown voltage | V _{(BR)DSS} | 40 | — | — | V | I _D = 10 mA, V _{GS} = 0 |
| Gate to source breakdown voltage | V _{(BR)GSS} | 16 | — | — | V | I _G = 800 μA, V _{DS} = 0 |
| | V _{(BR)GSS} | -2.5 | — | — | V | I _G = -100 μA, V _{DS} = 0 |
| Gate to source leak current | I _{GSS1} | — | — | 100 | μA | V _{GS} = 8 V, V _{DS} = 0 |
| | I _{GSS2} | — | — | 50 | μA | V _{GS} = 3.5 V, V _{DS} = 0 |
| | I _{GSS3} | — | — | 1 | μA | V _{GS} = 1.2 V, V _{DS} = 0 |
| | I _{GSS4} | — | — | -100 | μA | V _{GS} = -2.4 V, V _{DS} = 0 |
| Input current (shut down) | I _{GS(OP)1} | — | 0.8 | — | mA | V _{GS} = 8 V, V _{DS} = 0 |
| | I _{GS(OP)2} | — | 0.35 | — | mA | V _{GS} = 3.5 V, V _{DS} = 0 |
| Zero gate voltage drain current | I _{DSS} | — | — | 10 | μA | V _{DS} = 32 V, V _{GS} = 0, T _c = 110°C |
| Gate to source cutoff voltage | V _{GS(off)} | 1.1 | — | 2.1 | V | V _{DS} = 10 V, I _D = 1 mA |
| Forward transfer admittance | y _{fs} | 20 | 46 | — | S | I _D = 20 A, V _{DS} = 10 V ^{Note 5} |
| Static drain to source on state resistance | R _{DS(on)} | — | 11.3 | 15 | mΩ | I _D = 20 A, V _{GS} = 5 V ^{Note 5} |
| | R _{DS(on)} | — | 9 | 13 | mΩ | I _D = 20 A, V _{GS} = 10 V ^{Note 5} |
| Output capacitance | C _{oss} | — | 1098 | — | pF | V _{DS} = 10 V, V _{GS} = 0, f = 1MHz |
| Turn-on delay time | t _{d(on)} | — | 24.7 | — | μs | V _{GS} = 10 V, I _D = 20 A, R _L = 1.5 Ω |
| Rise time | t _r | — | 99.3 | — | μs | |
| Turn-off delay time | t _{d(off)} | — | 7.44 | — | μs | |
| Fall time | t _f | — | 13.3 | — | μs | |
| Body-drain diode forward voltage | V _{DF} | — | 0.9 | — | V | I _F = 40 A, V _{GS} = 0 ^{Note 5} |
| Body-drain diode reverse recovery time | t _{rr} | — | 122 | — | ns | I _F = 40 A, V _{GS} = 0 di/dt = 50 A/μs |
| Over load shut down operation time ^{Note 6} | t _{os1} | — | 0.63 | — | ms | V _{GS} = 5 V, V _{DD} = 16 V |

Notes: 5. Pulse test

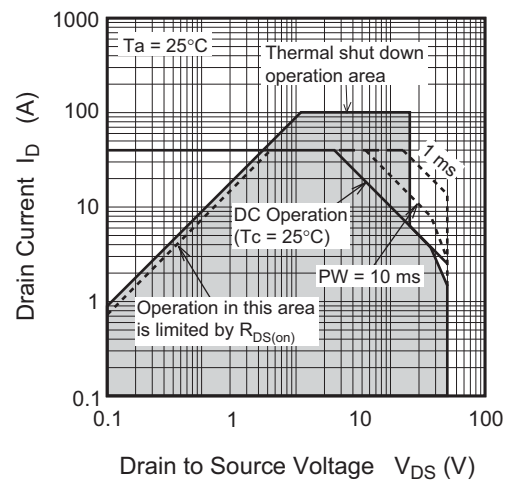
6. Including the junction temperature rise of the over loaded condition.

Main Characteristics

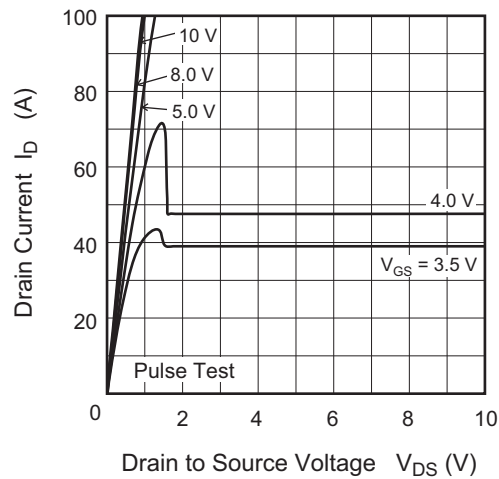
Power vs. Temperature Derating



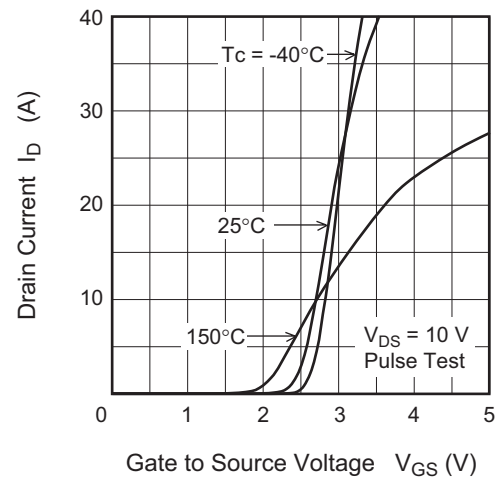
Maximum Safe Operation Area



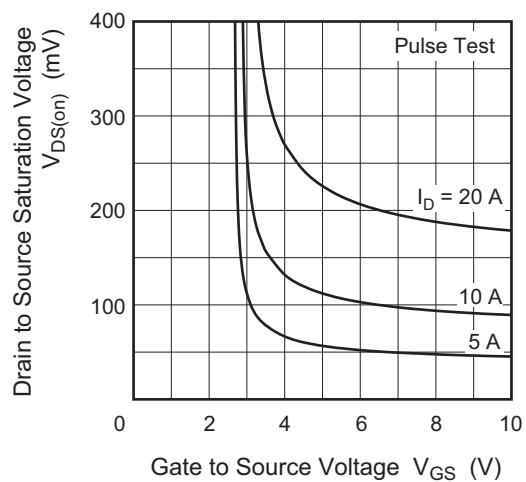
Typical Output Characteristics



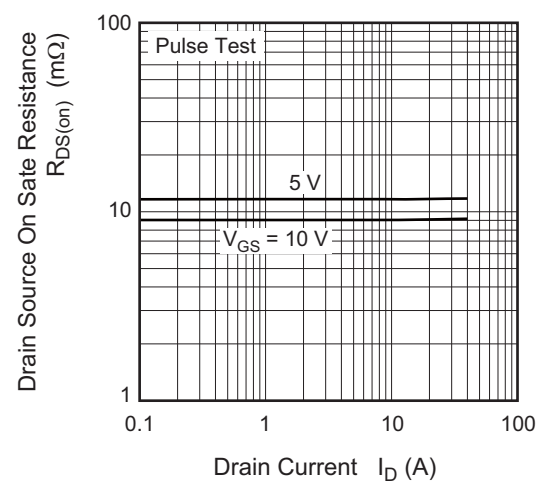
Typical Transfer Characteristics



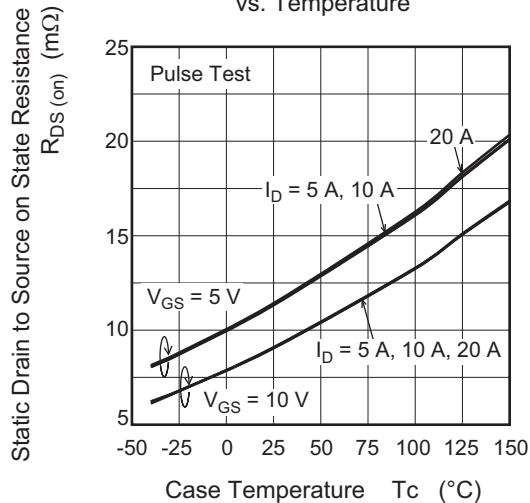
Drain to Source Saturation Voltage vs. Gate to Source Voltage



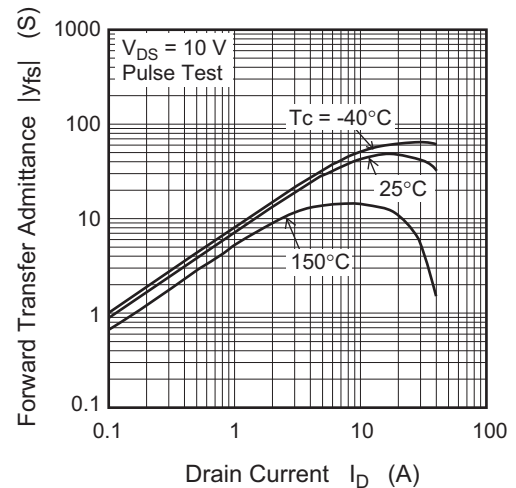
Static Drain to Source State Resistance vs. Drain Current



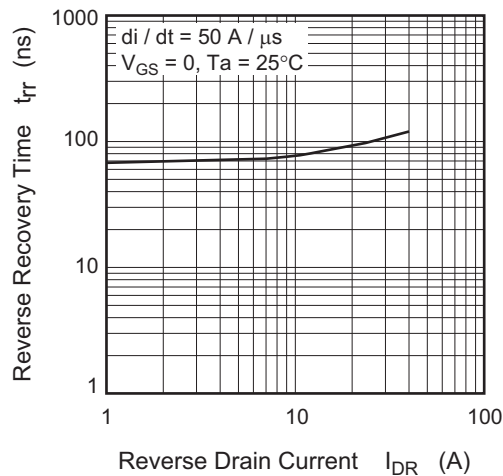
Static Drain to Source on State Resistance vs. Temperature



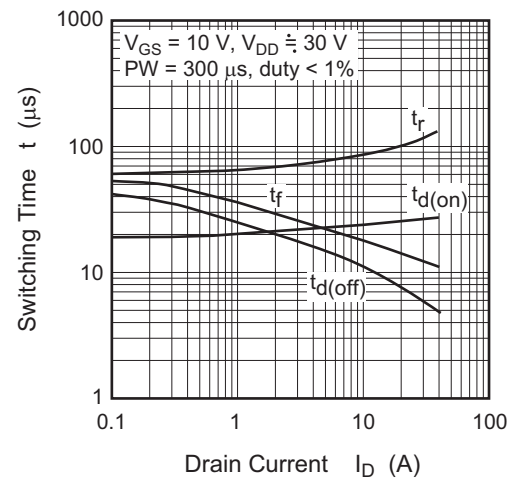
Forward Transfer Admittance vs. Drain Current



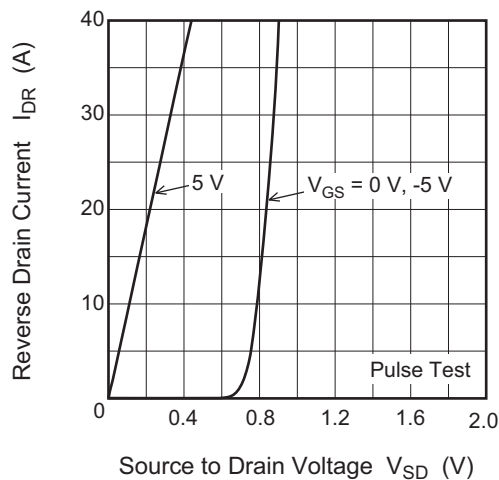
Body-Drain Diode Reverse Recovery Time



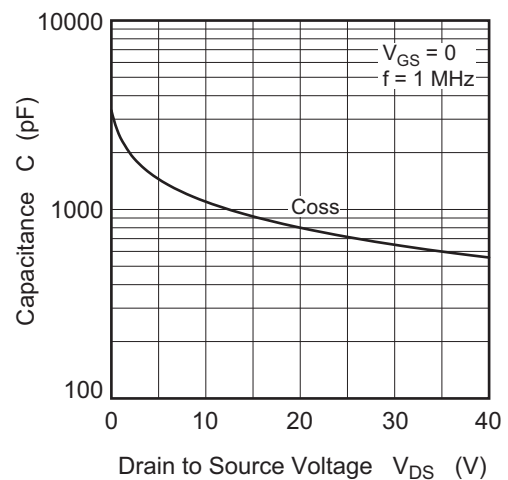
Switching Characteristics

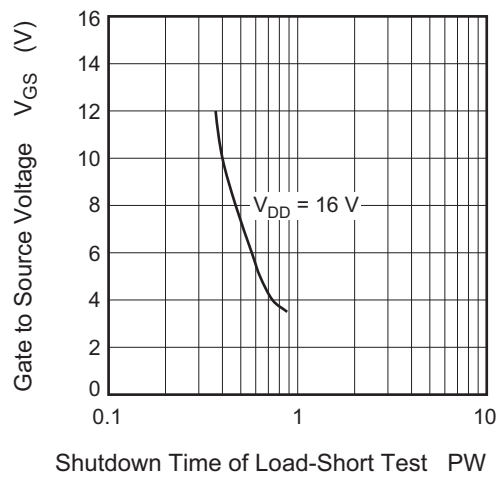
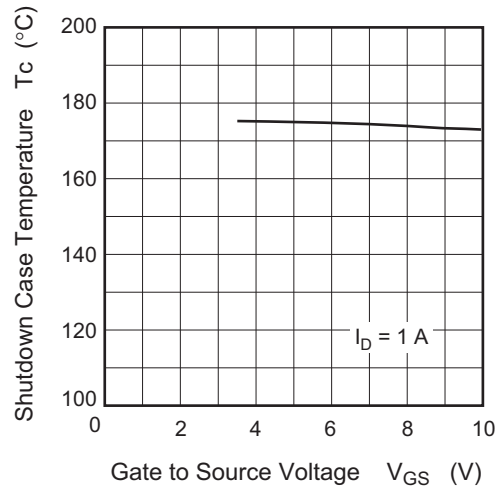


Reverse Drain Current vs. Source to Drain Voltage

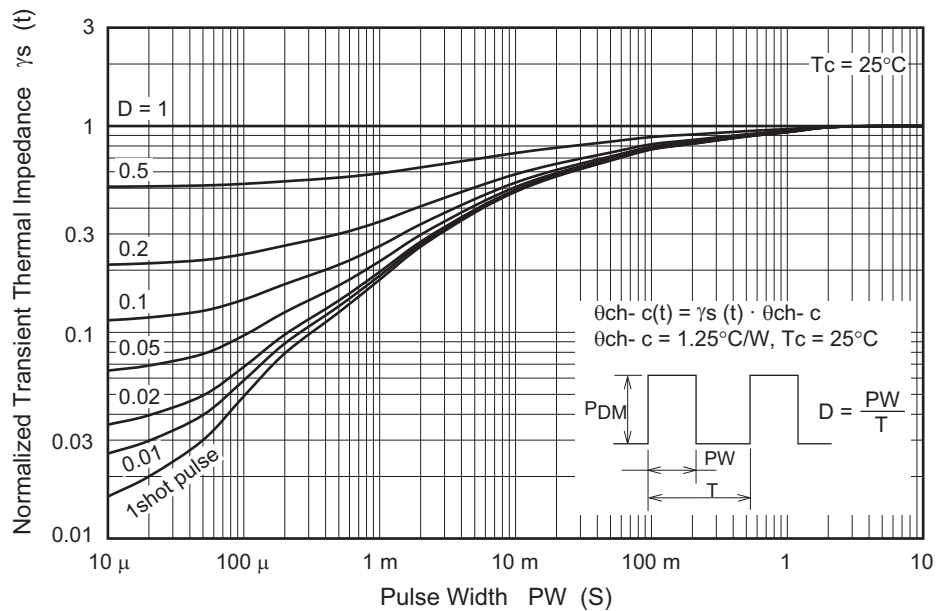


Typical Capacitance vs. Drain to Source Voltage

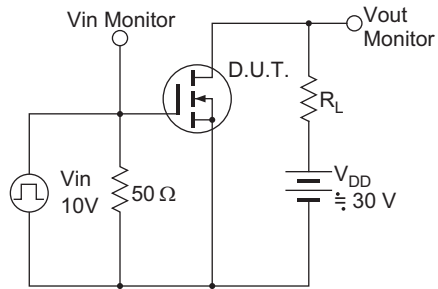


Gate to Source Voltage vs.
Shutdown Time of Load-Short TestShutdown Case Temperature vs.
Gate to Source Voltage

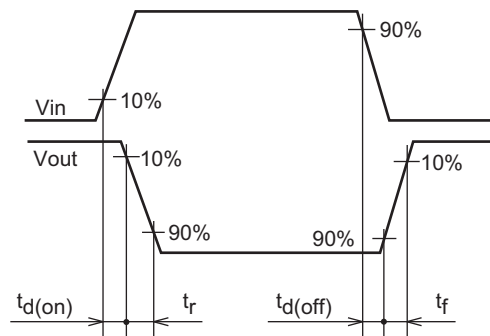
Normalized Transient Thermal Impedance vs. Pulse Width



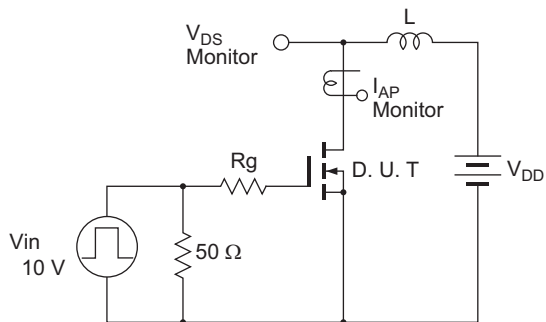
Switching Time Test Circuit



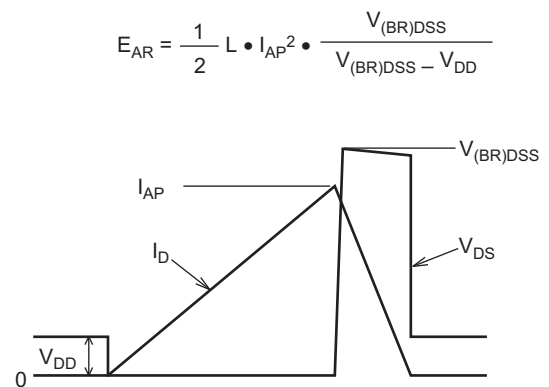
Waveform



Avalanche Test Circuit



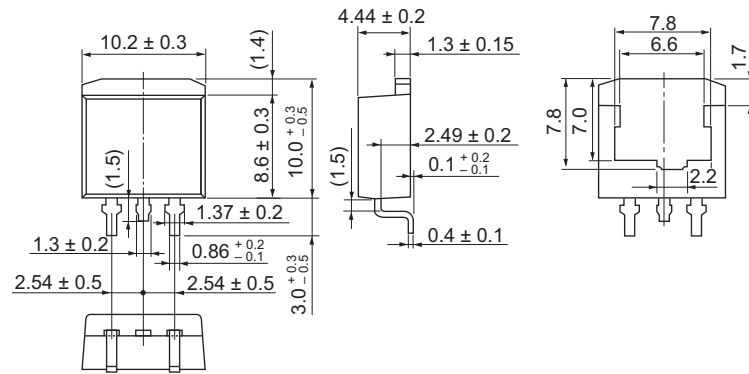
Avalanche Waveform



Package Dimensions

| Package Name | JEITA Package Code | RENESAS Code | Previous Code | MASS[Typ.] |
|---------------|--------------------|--------------|--------------------------------|------------|
| LDBPAK(S)-(1) | SC-83 | PRSS0004AE-B | LDBPAK(S)-(1) / LDBPAK(S)-(1)V | 1.30g |

Unit: mm



Ordering Information

| Orderable Part Number | Quantity | Shipping Container |
|-----------------------|----------|--------------------|
| RJF0410JPE-00-J3 | 1000 pcs | Taping |

Note: The symbol of 2nd "-" is occasionally presented as "#".

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Renesas Electronics America Inc.

2801 Scott Boulevard Santa Clara, CA 95050-2549, U.S.A.
Tel: +1-408-588-6000, Fax: +1-408-588-6130

Renesas Electronics Canada Limited

9251 Yonge Street, Suite 8309 Richmond Hill, Ontario Canada L4C 9T3
Tel: +1-905-237-2004

Renesas Electronics Europe Limited

Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K
Tel: +44-1628-585-100, Fax: +44-1628-585-900

Renesas Electronics Europe GmbH

Arcadiastrasse 10, 40472 Düsseldorf, Germany
Tel: +49-214-6503-0, Fax: +49-214-6503-1327

Renesas Electronics (China) Co., Ltd.

Room 1709, Quantum Plaza, No.27 ZhichunLu Haidian District, Beijing 100191, P.R.China
Tel: +86-10-8235-1155, Fax: +86-10-8235-7679

Renesas Electronics (Shanghai) Co., Ltd.

Unit 301, Tower A, Central Towers, 555 Langao Road, Putuo District, Shanghai, P. R. China 200333
Tel: +86-21-2226-0888, Fax: +86-21-2226-0999

Renesas Electronics Hong Kong Limited

Unit 1601-1611, 16/F., Tower 2, Grand Century Place, 193 Prince Edward Road West, Mongkok, Kowloon, Hong Kong
Tel: +852-2265-6688, Fax: +852 2886-9022

Renesas Electronics Taiwan Co., Ltd.

13F, No. 363, Fu Shing North Road, Taipei 10543, Taiwan
Tel: +886-2-8175-9600, Fax: +886 2-8175-9670

Renesas Electronics Singapore Pte. Ltd.

80 Bendemeer Road, Unit #06-02 Hyflux Innovation Centre, Singapore 339949
Tel: +65-6213-0200, Fax: +65-6213-0300

Renesas Electronics Malaysia Sdn.Bhd.

Unit 1207, Block B, Menara Amcorp, Amcorp Trade Centre, No. 18, Jln Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: +60-3-7955-9390, Fax: +60-3-7955-9510

Renesas Electronics India Pvt. Ltd.

No.777C, 100 Feet Road, HALII Stage, Indiranagar, Bangalore, India
Tel: +91-80-67208700, Fax: +91-80-67208777

Renesas Electronics Korea Co., Ltd.

12F., 234 Teheran-ro, Gangnam-Gu, Seoul, 135-080, Korea
Tel: +82-2-558-3737, Fax: +82-2-558-5141